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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Cheng-Lien Chiang  
Assignee: Bridge Semiconductor Corporation  
Title: METHOD OF MAKING A SEMICONDUCTOR PACKAGE DEVICE  
Serial No.: Unknown Filed: Herewith  
Examiner: Unknown Group Art Unit: Unknown  
Atty. Docket No.: BDG005-1

ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

**PRELIMINARY AMENDMENT**

Dear Sir:

Please amend the application as follows.

**In the Title**

The Title has been replaced with:

METHOD OF MAKING A SEMICONDUCTOR PACKAGE DEVICE

**In the Abstract**

The Abstract has been replaced with:

A method of making a semiconductor package device includes attaching a semiconductor chip to a metallic structure using an insulative adhesive, wherein the chip includes a conductive pad, the metallic structure includes first and second opposing surfaces and a conductive trace, the adhesive is disposed between the first surface and the chip, the conductive trace includes a